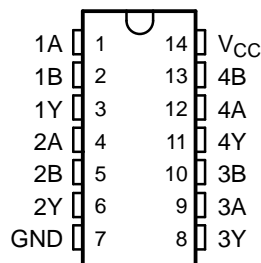


FEATURES

- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 2.8 ns at 3.3 V
- ± 24 -mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

D, DGV, NS, OR PW PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This quadruple 2-input positive-OR gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVC32 performs the Boolean function $Y = \overline{A} \cdot \overline{B}$ or $Y = A + B$ in positive logic.

ORDERING INFORMATION

| T_A | PACKAGE ⁽¹⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---------------|------------------------|---------------|-----------------------|------------------|
| -40°C to 85°C | SOIC - D | Tube | SN74ALVC32D | ALVC32 |
| | | Tape and reel | SN74ALVC32DR | |
| | SOP - NS | Tape and reel | SN74ALVC32NSR | ALVC32 |
| | TSSOP - PW | Tube | SN74ALVC32PW | VA32 |
| | | Tape and reel | SN74ALVC32PWR | |
| | TVSOP - DGV | Tape and reel | SN74ALVC32DGVR | VA32 |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each gate)

| INPUTS | | OUTPUT |
|--------|---|--------|
| A | B | Y |
| H | X | H |
| X | H | H |
| L | L | L |

LOGIC DIAGRAM, EACH GATE (POSITIVE LOGIC)



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SN74ALVC32

QUADRUPLE 2-INPUT POSITIVE-OR GATE

SCES108G—JULY 1997—REVISED NOVEMBER 2004

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|------------------|---|--------------------|------|-----------------------|------|
| V _{CC} | Supply voltage range | | -0.5 | 4.6 | V |
| V _I | Input voltage range ⁽²⁾ | | -0.5 | 4.6 | V |
| V _O | Output voltage range ⁽²⁾⁽³⁾ | | -0.5 | V _{CC} + 0.5 | V |
| I _{IK} | Input clamp current | V _I < 0 | | -50 | mA |
| I _{OK} | Output clamp current | V _O < 0 | | -50 | mA |
| I _O | Continuous output current | | | ±50 | mA |
| | Continuous current through V _{CC} or GND | | | ±100 | mA |
| θ _{JA} | Package thermal impedance ⁽⁴⁾ | D package | | 86 | °C/W |
| | | DGV package | | 127 | |
| | | NS package | | 76 | |
| | | PW package | | 113 | |
| T _{stg} | Storage temperature range | | -65 | 150 | °C |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

| | | MIN | MAX | UNIT |
|---------------------|------------------------------------|--|----------------------|------|
| V_{CC} | Supply voltage | 1.65 | 3.6 | V |
| V_{IH} | High-level input voltage | $V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$ | $0.65 \times V_{CC}$ | V |
| | | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | 1.7 | |
| | | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ | 2 | |
| V_{IL} | Low-level input voltage | $V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$ | $0.35 \times V_{CC}$ | V |
| | | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | 0.7 | |
| | | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$ | 0.8 | |
| V_I | Input voltage | 0 | 3.6 | V |
| V_O | Output voltage | 0 | V_{CC} | V |
| I_{OH} | High-level output current | $V_{CC} = 1.65 \text{ V}$ | -4 | mA |
| | | $V_{CC} = 2.3 \text{ V}$ | -12 | |
| | | $V_{CC} = 2.7 \text{ V}$ | -12 | |
| | | $V_{CC} = 3 \text{ V}$ | -24 | |
| I_{OL} | Low-level output current | $V_{CC} = 1.65 \text{ V}$ | 4 | mA |
| | | $V_{CC} = 2.3 \text{ V}$ | 12 | |
| | | $V_{CC} = 2.7 \text{ V}$ | 12 | |
| | | $V_{CC} = 3 \text{ V}$ | 24 | |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | | 5 | ns/V |
| T_A | Operating free-air temperature | -40 | 85 | °C |

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|------------------|--|-----------------|-----------------------|--------------------|-----|------|
| V _{OH} | I _{OH} = -100 µA | 1.65 V to 3.6 V | V _{CC} - 0.2 | | | V |
| | I _{OH} = -4 mA | 1.65 V | 1.2 | | | |
| | I _{OH} = -6 mA | 2.3 V | 2 | | | |
| | I _{OH} = -12 mA | 2.3 V | 1.7 | | | |
| | | 2.7 V | 2.2 | | | |
| | | 3 V | 2.4 | | | |
| | I _{OH} = -24 mA | 3 V | 2 | | | |
| V _{OL} | I _{OL} = 100 µA | 1.65 V to 3.6 V | 0.2 | | | V |
| | I _{OL} = 4 mA | 1.65 V | 0.45 | | | |
| | I _{OL} = 6 mA | 2.3 V | 0.4 | | | |
| | I _{OL} = 12 mA | 2.3 V | 0.7 | | | |
| | | 2.7 V | 0.4 | | | |
| | I _{OL} = 24 mA | 3 V | 0.55 | | | |
| I _I | V _I = V _{CC} or GND | 3.6 V | ±5 | | | µA |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 3.6 V | 10 | | | µA |
| ΔI _{CC} | One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND | 3 V to 3.6 V | 750 | | | µA |
| C _i | V _I = V _{CC} or GND | 3.3 V | 4 | | | pF |

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

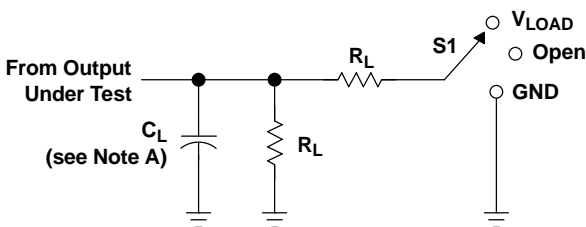
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 1.8 V ± 0.15 V | | V _{CC} = 2.5 V ± 0.2 V | | V _{CC} = 2.7 V | | V _{CC} = 3.3 V ± 0.3 V | | UNIT |
|-----------------|-----------------|----------------|-------------------------------------|-----|------------------------------------|-----|-------------------------|-----|------------------------------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A or B | Y | 1 | 4.7 | 1 | 3.1 | 2.9 | | 1 | 2.8 | ns |

OPERATING CHARACTERISTICS

T_A = 25°C

| PARAMETER | TEST CONDITIONS | V _{CC} = 1.8 V ± 0.15 V | V _{CC} = 2.5 V ± 0.2 V | V _{CC} = 3.3 V ± 0.3 V | UNIT |
|--|--------------------------------|-------------------------------------|------------------------------------|------------------------------------|------|
| | | TYP | TYP | TYP | |
| C _{pd} Power dissipation capacitance per gate | C _L = 0, f = 10 MHz | 23 | 24 | 26 | pF |

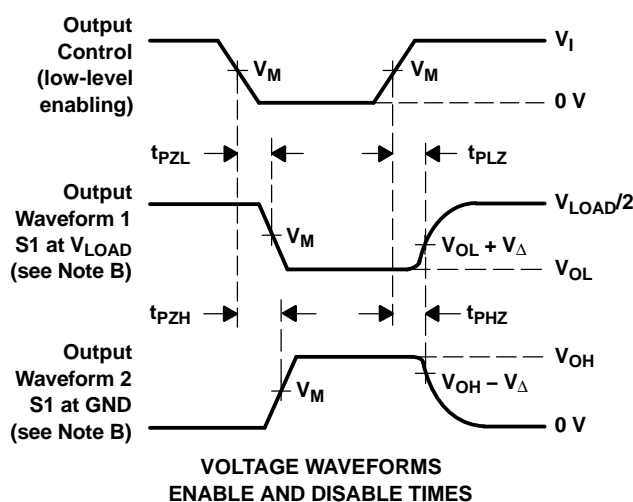
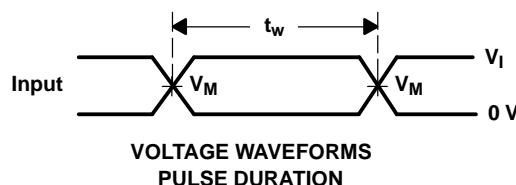
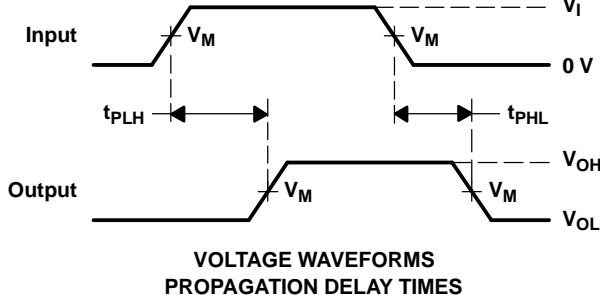
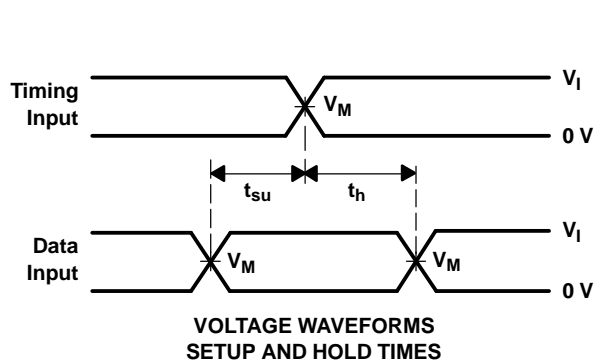
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

| TEST | S1 |
|-------------------|------------|
| t_{pd} | Open |
| t_{PLZ}/t_{PZL} | V_{LOAD} |
| t_{PHZ}/t_{PHL} | GND |

| V_{CC} | INPUT | | V_M | V_{LOAD} | C_L | R_L | V_{Δ} |
|----------------------------------|----------|----------------------|------------|-------------------|-------|--------------|--------------|
| | V_I | t_r/t_f | | | | | |
| $1.8\text{ V} \pm 0.15\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 k Ω | 0.15 V |
| $2.5\text{ V} \pm 0.2\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| 2.7 V | 2.7 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| $3.3\text{ V} \pm 0.3\text{ V}$ | 2.7 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-012 variation AB.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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